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(54) Title: DEVICE AND THERMAL TESTER FOR THERMAL TESTING DIES OF AN INTEGRATED CIRCUIT

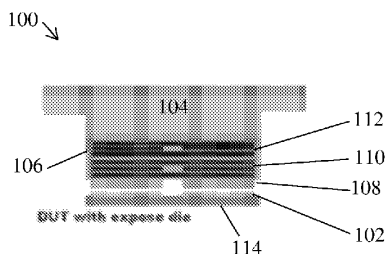


FIG. 1A

(57) Abstract: A device for thermal testing one or more exposed or covered dies of an integrated circuit and a thermal tester for testing one or more exposed or covered dies of an integrated circuit on a testing platform are provided. The device for thermal testing the one or more exposed or covered dies of the integrated circuit includes a pedestal and a heatlet attached to a first end of the pedestal. The heatlet includes a face comprising one or more plates. The one or more plates are configured to match a geometry of the one or more dies. The heatlet also includes heating circuitry configured in operation to heat the one or more plates of the face and sensing circuitry configured in operation to sense a temperature of the heatlet.

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